

## PMP10961 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1	1	0.1uF	C1005X7R1H104K	TDK	CAP, CERM, 0.1 $\mu$ F, 50 V, +/- 10%, X7R, 0402	0402
C2	1	0.1uF	C0603C104J3RACTU	Kemet	CAP, CERM, 0.1uF, 25V, +/-5%, X7R, 0603	0603
C4	1	68uF	16TQC68MYF	Panasonic	CAP, Tantalum Polymer, 68 $\mu$ F, 16 V, +/- 20%, 0.05 ohm, 7.3x2.0x4.3mm SMD	7.3x2.0x4.3mm
C5, C6	2	470uF	4TPF470ML	Panasonic	CAP, Tantalum Polymer, 470 $\mu$ F, 4 V, +/- 20%, 0.01 ohm, 7.3x2.8x4.3mm SMD	7.3x2.8x4.3mm
C7, C8, C9, C10	4	10uF	GRM31CR61C106KA88L	MuRata	CAP, CERM, 10 $\mu$ F, 16 V, +/- 10%, X5R, 1206	1206
C11	1	2.2uF	GRM188R61C225KE15D	MuRata	CAP, CERM, 2.2 $\mu$ F, 16 V, +/- 10%, X5R, 0603	0603
C12, C13, C14, C15	4	47uF	C3216X5R0J476M	TDK	CAP, CERM, 47 $\mu$ F, 6.3 V, +/- 20%, X5R, 1206	1206
C17, C18	2	4.7uF	GRM188R61C475KAAJ	MuRata	CAP, CERM, 4.7 $\mu$ F, 16 V, +/- 10%, X5R, 0603	0603
C19	1	1000pF	GRM188R61H102KA01D	MuRata	CAP, CERM, 1000 pF, 50 V, +/- 10%, X5R, 0603	0603
J1	1		U.FL-R-SMT-1	Hirose Electric Co. Ltd.	Connector, Ultra-Mini Coaxial, SMD	Ultra small CO-AX SMD
J2, J3	2		ED120/2DS	On-Shore Technology	TERMINAL BLOCK 5.08MM VERT 2POS, TH	TERM_BLK, 2pos, 5.08mm
J4	1		5103308-1	TE Connectivity	Header (shrouded), 100mil, 5x2, Gold, TH	5x2 Shrouded header
J5	1		800-10-002-10-001000	Mill-Max	Header, 100mil, 2x1, TH	Header, 2x1, 100mil, TH
L1	1	1uH	XAL7070-102MEB	Coilcraft	Inductor, Shielded, Composite, 1 $\mu$ H, 25 A, 0.00255 ohm, SMD	7.2x7x7.5mm
R1, R6	2	49.9	CRCW040249R9FKED	Vishay-Dale	RES, 49.9, 1%, 0.063 W, 0402, RES, 49.9 ohm, 1%, 0.063W, 0402	0402
R2, R18	2	100k	CRCW0402100KFKED	Vishay-Dale	RES, 100 k, 1%, 0.063 W, 0402	0402
R3	1	20.0k	CRCW040220K0FKED	Vishay-Dale	RES, 20.0 k, 1%, 0.063 W, 0402	0402
R4, R16	2	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0 ohm, 5%, 0.063W, 0402	0402
R5	1	57.6k	CRCW040257K6FKED	Vishay-Dale	RES, 57.6 k, 1%, 0.063 W, 0402	0402
R9	1	1.0	CRCW04021R00JNED	Vishay-Dale	RES, 1.0, 5%, 0.063 W, 0402	0402
R10, R11	2	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
R13, R17	2	200k	CRCW0402200KFKED	Vishay-Dale	RES, 200 k, 1%, 0.063 W, 0402	0402
R14	1	2.2	CRCW08052R20JNEA	Vishay-Dale	RES, 2.2, 5%, 0.125 W, 0805	0805
R15	1	120k	CRCW0402120KFKED	Vishay-Dale	RES, 120 k, 1%, 0.063 W, 0402	0402
U1	1		TPS53915RVE	Texas Instruments	High Performance, 12-A Single Synchronous Step-Down Converter with PMBus, RVE0028A	RVE0028A
C3	0	0.01uF	C1005X7R1C103K	TDK	CAP, CERM, 0.01 $\mu$ F, 16 V, +/- 10%, X7R, 0402	0402
C16	0	1000pF	C1005X7R1H102K	TDK	CAP, CERM, 1000pF, 50V, +/-10%, X7R, 0402	0402
R7	0	2.49k	CRCW04022K49FKED	Vishay-Dale	RES, 2.49 k, 1%, 0.063 W, 0402	0402
R8	0	150k	CRCW0402150KFKED	Vishay-Dale	RES, 150 k, 1%, 0.063 W, 0402	0402
R12	0	100k	CRCW0402100KFKED	Vishay-Dale	RES, 100 k, 1%, 0.063 W, 0402	0402

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